

Würth Elektronik eiSos GmbH & Co. KG

EMC & Inductive Solutions

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Product / Process Change Notification (PCN)

- Major change
 Minor change

PCN #: PCN_IndGF_20200207

Affected Series: WE-GF; 1210 744764xxx, 1812 744766xxx

PCN Date: November 07, 2019

Effective Date: February 07, 2020

Change Category:

- Equipment / Location
 General Data
 Material
 Process
 Product Design
 Shipping / Packaging
 Supplier
 Software

Contact: Product Management

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Data Sheet Change:

Yes No

Attachment:

Yes No

DESCRIPTION AND PURPOSE OF CHANGE:

Because of a database mismatch, Würth Elektronik will correct the reflow specification to 245°C max. for 10s max. and will correct the MSL (moisture sensitivity level) to 3 in the datasheet of the product series WE-GF.

All products with date code 2019-11-07 or later, will be affected by this data sheet correction.

This is a datasheet correction only. There will be no change in form, fit, function, quality or reliability of the product.

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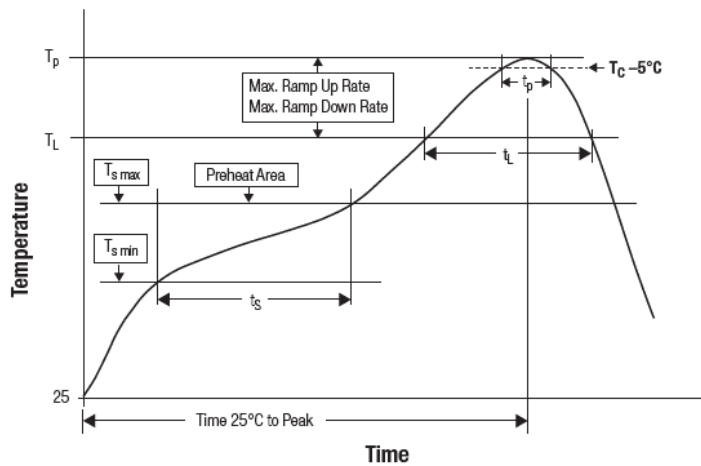


DETAIL OF CHANGE:

Reflow Profile:

current

Classification Reflow Profile for SMT components:



Profile Feature		Value
Preheat Temperature Min	$T_{s\ min}$	150 °C
Preheat Temperature Max	$T_{s\ max}$	200 °C
Preheat Time t_s from $T_{s\ min}$ to $T_{s\ max}$	t_s	60 - 120 seconds
Ramp-up Rate (T_L to T_p)		3 °C/ second max.
Liquidous Temperature	T_L	217 °C
Time t_L maintained above T_L	t_L	60 - 150 seconds
Peak package body temperature	T_p	see table below
Time within 5 °C of actual peak temperature	t_p	20 - 30 seconds
Ramp-down Rate (T_L to T_p)		6 °C / second max.
Time 25 °C to peak temperature		8 minutes max.

Package Classification Reflow Temperature:

Properties	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly Package Thickness < 1.6 mm	260 °C	260 °C	260 °C
PB-Free Assembly Package Thickness 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
PB-Free Assembly Package Thickness ≥ 2.5 mm	250 °C	245 °C	245 °C

refer to IPC/ JEDEC J-STD-020E

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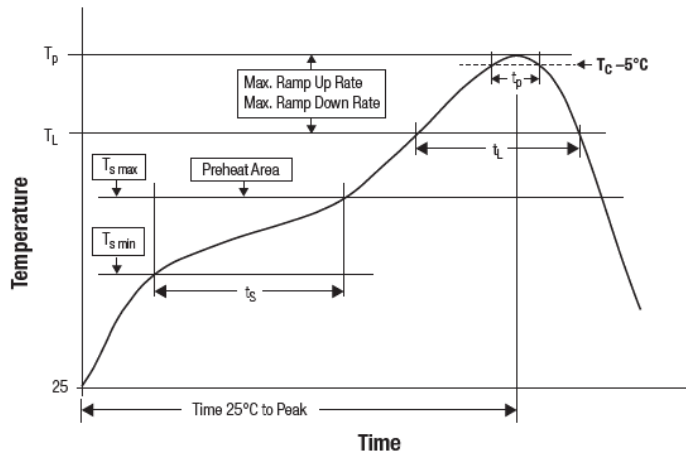
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will change to

Classification Reflow Profile for SMT components:



Profile Feature		Value
Preheat Temperature Min	$T_{s \text{ min}}$	150 °C
Preheat Temperature Max	$T_{s \text{ max}}$	200 °C
Preheat Time t_s from $T_{s \text{ min}}$ to $T_{s \text{ max}}$	t_s	60 - 120 seconds
Ramp-up Rate (T_L to T_p)		3 °C/ second max.
Liquidous Temperature	T_L	217 °C
Time t_L maintained above T_L	t_L	60 - 150 seconds
Peak package body temperature	T_p	245 °C max.
Time within 5 °C of actual peak temperature	t_p	10 seconds max.
Ramp-down Rate (T_L to T_p)		6 °C / second max.
Time 25 °C to peak temperature		8 minutes max.

closely based on IPC / JEDEC-J-STD-020E

MS Level:

The change from MSL 1 to level 3 will implemented in datasheet as well.

The storage temperature (in original packing) will change:

from MSL1: -20°C up to +40°C, 75% RH max.

to MSL3: < 40 °C ; < 90 % RH.

RELIABILITY / QUALIFICATION SUMMARY:

Classification test according IPC / JEDEC-J-STD-020E plus 3 times reflow was performed.